

Electronic Patent Application Fee Transmittal

Application Number:	10588473
Filing Date:	01-Aug-2006
Title of Invention:	Optimized Contact Design for Thermosonic Bonding of Flip-Chip Devices
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Filer:	Robert Michael Sieg/Mary Ann Temesvari
Attorney Docket Number:	GLOZ 2 00201

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	490	490

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				490